



## Material Content Data Sheet



<b>Sales Product Name</b>		BBY 55-02V H6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000787824						
<b>Package</b>		PG-SC79-2-1		<b>Weight*</b>		1.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		24	
	noble metal	gold	7440-57-5	0.004	0.23		2331	
	inorganic material	silicon	7440-21-3	0.033	1.99	2.22	19908	22263
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		92	
	non noble metal	titanium	7440-32-6	0.001	0.05		459	
	non noble metal	chromium	7440-47-3	0.002	0.14		1377	
	non noble metal	copper	7440-50-8	0.767	45.72	45.92	457276	459204
wire	non noble metal	copper	7440-50-8	0.007	0.42	0.42	4154	4154
encapsulation	organic material	carbon black	1333-86-4	0.007	0.43		4292	
	plastics	epoxy resin	-	0.122	7.30		72971	
	inorganic material	silicondioxide	60676-86-0	0.591	35.20	42.93	351976	429239
leadfinish	non noble metal	tin	7440-31-5	0.055	3.25	3.25	32527	32527
plating	noble metal	silver	7440-22-4	0.088	5.26	5.26	52613	52613
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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